



Recommended PCB Layout
(top view)

Materials and Finish

Housing Material:
high temp. thermoplastic,
(reflow process compatible)
UL 94V-0 rated, black color

Recommended Reflow Temperature:
230°C for 30 seconds,
260°C max.

Design meets UL 1863 Sec. 8
Electrical Probe and Sec. 20
Child Finger test requirements

Contact Material: phosphor bronze

Contact Plating Options:
Standard: 0.0001" Nickel
Plating, Selective Plating
Gold Flash on Contact
Area, Tin/Lead on Termination End
-50 Option: 0.0001" Nickel Plating,
Selective Plating 0.000050"
Gold on Contact Area to
Comply with FCC Requirements
Under No. 47 C.F.R. Part 68,
Subpart F, Tin/Lead on
Termination End

Electrical Characteristics

Insulation Resistance:
500 Megohms min.
Dielectric Withstanding Voltage:
1000V rms, 60Hz
Contact Resistance:
20 milliohms max.
Current Rating: 1.5 Amps
Durability Rating:
1000 mating cycles min.
Operating Temperature:
-40°C to +85°C

| Part Number | Contact Area Plating | Packaging |
|-------------------|-----------------------|-------------|
| GM-SMT4-N-66 | Gold Flash (standard) | Bulk |
| GM-SMT4-N-66-50 | 50u" Gold (50 option) | |
| GM-SMT4-N-66-TR | Gold Flash (standard) | Tape & Reel |
| GM-SMT4-N-66-50TR | 50u" Gold (50 option) | |



| Tolerances |
|----------------------------|
| X.X ± 0.38 |
| X.XX ± 0.25 |
| Unless Stated Otherwise |

| REVISION | DATE | DESCRIPTION | DRAWN BY | DESIGNED BY | UNITS |
|----------|---------|----------------|------------|-------------|----------|
| A2 | 6/18/01 | REF ECD 01-113 | E. Cruz | | mm |
| A3 | 3/25/02 | REF ECD 01-199 | REVISED BY | APPROVED BY | DATE |
| A4 | 6/5/02 | REF ECD 02-038 | C. Leiva | | 12/15/00 |

GM-SMT4-N-66

Right Angle Modular Jack--No Pegs
6 position, 6 contacts, Surface Mount

